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April 1st, 2010
Renesas Electronics Corporation

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H8S/2552, H8S/2506 Group
BP-176V User System Interface
Cable for E6000 Emulator

HS2552ECB62H User's Manual

Renesas Microcomputer
Development Environment
System

H8S Family / H8S/2500 Series

HS2552ECB62HE

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Preface

Thank you for purchasing this user system interface cable (HS2552ECB62H) for the Renesas' original microcomputers H8S/2552 and H8S/2506 group.

The HS2552ECB62H is a user system interface cable that connects the H8S/2552 and H8S/2506 group E6000 emulator (HS2556EPI61H; hereinafter referred to as the emulator) to the IC socket for a BP-176V package for the H8S/2552 or H8S/2506 group MCU on the user system.

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Section 1 Configuration

CAUTION

Use a CSPACK176A1513H01 socket (manufactured by Tokyo Eletech Corporation) for the BP-176V package IC socket on the user system.

Figure 1 shows the configuration of the HS2552ECB62H user system interface cable for the BP-176V package.

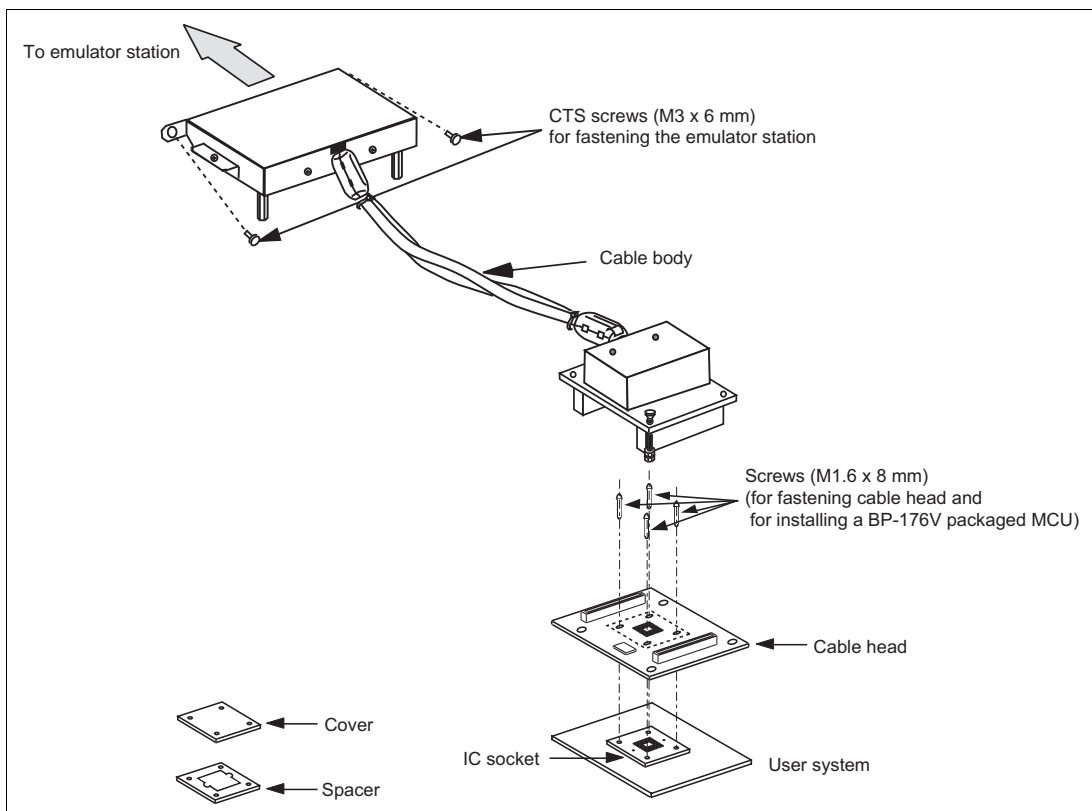


Figure 1 HS2552ECB62H User System Interface Cable

Table 1 lists the HS2552ECB62H components. Please make sure you have all of these components when unpacking.

Table 1 HS2552ECB62H Components

No.	Component	Quantity	Remarks
1	Cable body	1	Includes coaxial cable
2	Cable head	1	
3	IC socket	1	For the BP-176V package
4	Spacer	1	For installing a BP-176V packaged MCU
5	Cover	1	For installing a BP-176V packaged MCU
6	Screws (M1.6 x 8 mm)	4	For fastening cable head
7	Screws (M1.6 x 10 mm)	4	For installing a BP-176V packaged MCU
8	Driver	1	Screwdriver dedicated for fastening the screws
9	CTS Screws (M3 x 6 mm)	2	For fixing the cable body
10	Documentation	1	User's manual for HS2552ECB62H (this manual)

Section 2 Connection Procedures

2.1 Connecting User System Interface Cable to Emulator Station

WARNING

Observe the precautions listed below. Failure to do so will result in a FIRE HAZARD and will damage the user system and the emulator product or will result in PERSONAL INJURY. The USER PROGRAM will be LOST.

- 1. Always switch OFF the user system and the emulator product before the USER SYSTEM INTERFACE CABLE is connected to or removed from any part. Before connecting, make sure that pin 1 on both sides are correctly aligned.**
- 2. The user system interface cable dedicated to the emulator must be used.**

To connect the cable body to the emulator station, follow the instructions below.

1. Make sure the user system and emulator station are turned off.

CAUTION

When connecting or removing the user system interface cable, apply force only in the direction suitable for connection or removal, while making sure not to bend or twist the cable or connectors. Otherwise, the connectors will be damaged.

2. After making sure the direction of the cable body connector is correct, firmly insert the cable body connector into the emulator station socket (figure 2).

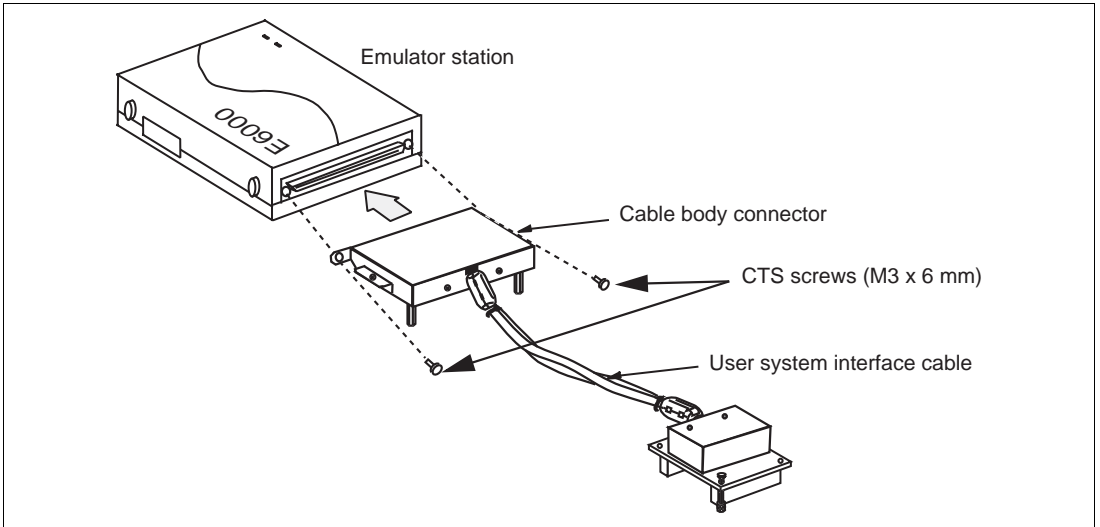


Figure 2 Connecting User System Interface Cable to Emulator Station

2.2 Connecting User System Interface Cable to User System

WARNING

Always switch OFF the user system and the emulator product before the USER SYSTEM INTERFACE CABLE is connected to or removed from any part. Before connecting, make sure that pin 1 on both sides are correctly aligned. Failure to do so will result in a FIRE HAZARD and will damage the user system and the emulator product or will result in PERSONAL INJURY. The USER PROGRAM will be LOST.

To connect the cable head to the user system, follow the instructions below.

2.2.1 Soldering the IC Socket

Install the socket for BP-176V-packaged ICs on the user system.

- (1) Gently apply solder to the BGA pads of the user system. Be careful to keep the thickness of the solder within 100 to 150 μm . Too much solder will cause short-circuiting of the pins.
- (2) The IC socket is vacuum-packed to avoid oxidization of the surfaces of the solder balls. It is thus recommended that the IC socket be installed on the user system if you do not install the socket immediately after the package it comes in is opened. After the package's seal has been broken, store the socket in a desiccator. Do not touch the solder balls. If they are touched, solder may not adhere to the solder surface.
The IC socket is covered by a protective cover. Socket and cover are fastened together by four screws before the whole is vacuum packed to prevent bending of the IC socket's pins. To avoid the scattering (dispersal) of flux from other components to the IC socket, keep the protective cover on the IC socket until solder reflow has been completed.
- (3) Install the provided guide pins into the holes for the guide pins on the user system. Check that the pads are correctly aligned with the IC socket.

(4) Notes on soldering the IC socket

- a. The IC socket is larger than the actual IC package; therefore, refer to figure 7 for the installation of other components.
- b. Do not install components that occupy large volume close to the IC socket. Such components will prevent the convective flow of heat during reflow.
- c. Since the IC socket has a greater volume than the IC package, it is recommended that the temperature profile under the conditions used in installation be measured by attaching a temperature sensor to the back side of the IC socket.
- d. Under the reflow conditions for soldering the IC socket, specify the actual heating to more than 210°C for 30 to 60 seconds.

Recommended Reflow Conditions

Surface temperature of IC-socket connector

Preheating: 150 to 180°C for 180 seconds

Actual heating: To more than 210°C, for 30 to 60 seconds

CAUTION

- 1. Never dip the IC socket in flux or use wash to clean the IC socket. This is because flux may remain inside the IC socket due to the IC socket's structure. When using the IC socket with other DIP products, never clean the other DIP products with flux because the flux may enter the connector through the guide pins of the IC socket.**
- 2. When an IC socket with guide pins is soldered to the user system, about 1.4 mm of the guide pins will stick out (when the user-system board is 1.6 mm thick). When a load is applied to the guide pins from the back of the user-system board, stress will be applied to the soldered part of the IC socket, and this may destroy the connectors. Do not apply any load to the guide pins after the IC socket has been soldered on the user system.**
- 3. When an IC socket with no guide pins is soldered to the user system, the soldered part will crack if stress is applied to the IC socket. Therefore, always apply adhesive to the connector and the user system so that there is a firm connection between them.**
- 4. When the IC socket has guide pins, it is recommended that epoxy resin adhesive or solder be applied to the guide pins at the back of the user system to make sure that no stress is applied to the soldered part.**

2.2.2 Inserting Cable Head

CAUTION

Check the location of pin 1 before inserting.

Align pin 1 on the IC socket for a BP-176V package on the user system with pin 1 on the user system interface cable head, and insert the user system interface cable head into the IC socket on the user system, as shown in figure 3.

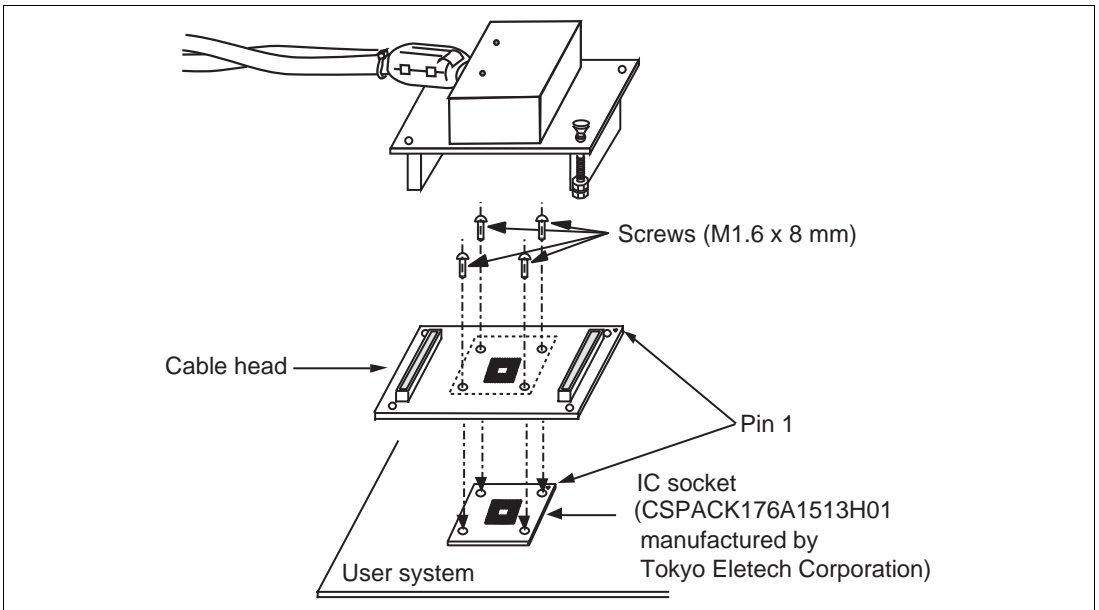


Figure 3 Connecting User System Interface Cable to User System

2.2.3 Fastening Cable Head

CAUTION

1. Use the screwdriver whose head matches the screw head.
2. The tightening torque must be 0.054 N•m or less.
If the applied torque cannot be accurately measured, stop tightening when the force required to turn the screw becomes significantly greater than that needed when first tightening. If a screw is tightened too much, the screw head will break or an IC socket contact error will be caused by a crack in the IC socket solder.
3. If the emulator does not operate correctly, cracks might have occurred in the solder.

Use four screws (M1.6 × 8 mm) to fix the user system interface cable (HS2552ECB62H) head to the IC socket for the BP-176V package on the user system. Follow the procedure below to fasten the cable head.

1. Insert two screws (M1.6 × 8 mm) to 1 and 3, and screw it a little so that holes at 2-2' and 4-4' match, respectively.

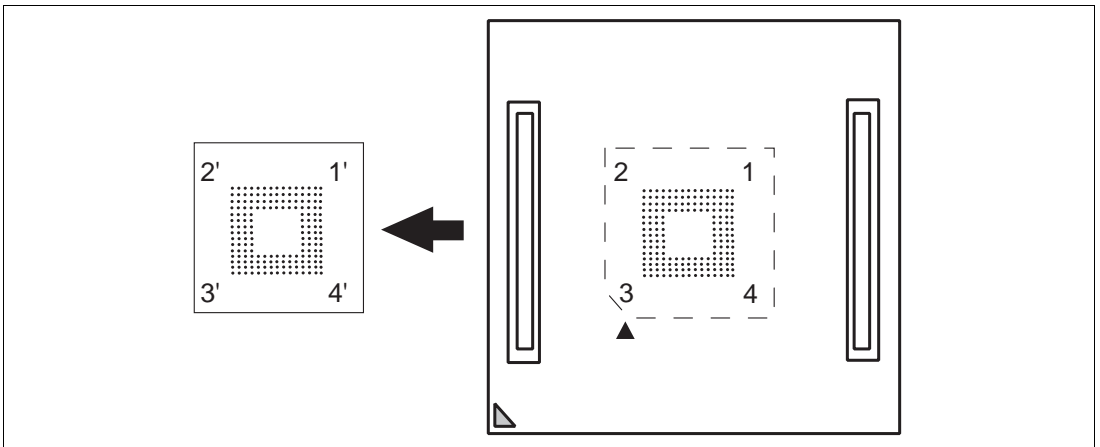


Figure 4 Fastening Cable Head Procedure (1)

2. Fasten screws to 2 and 4 a little, so that four screw holes are aligned. Then, each screw should be tightened a little at a time, alternating between screws on opposing corners.

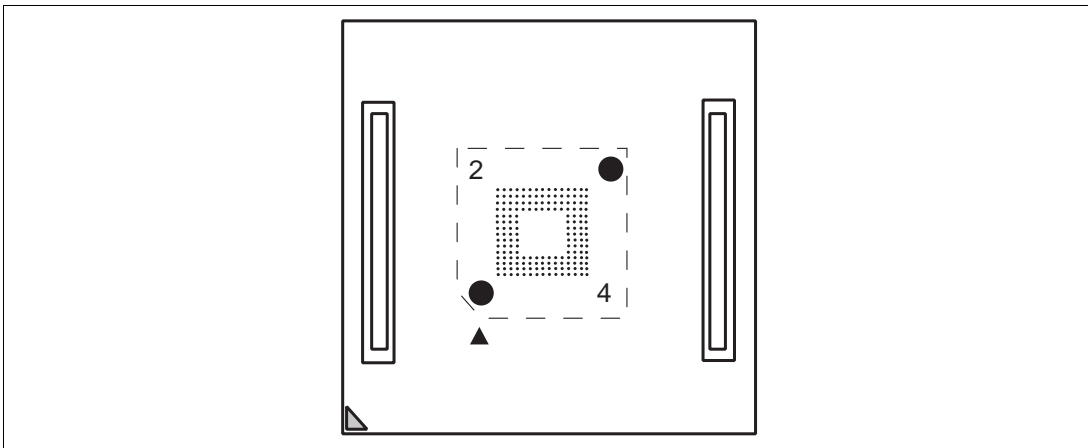


Figure 5 Fastening Cable Head Procedure (2)

2.2.4 Fastening Cable Body

Connect the cable body to the cable head.

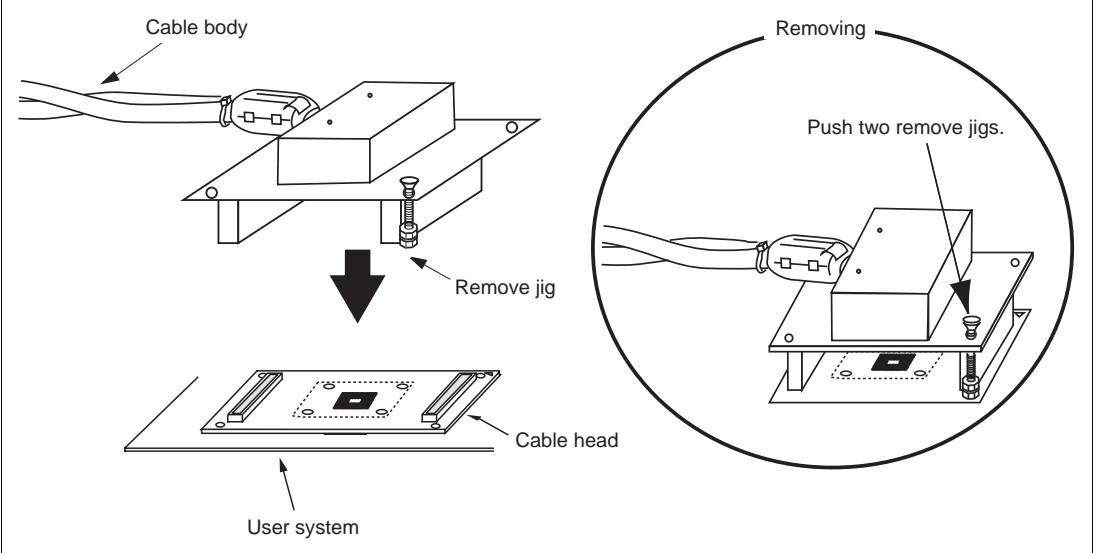


Figure 6 Fastening Cable Body

2.3 Recommended Dimensions for User System Mount Pad

Figure 7 shows the recommended dimensions for the mount pad (footprint) for the user system with an IC socket for a BP-176V package (CSPACK176A1513H01: manufactured by Tokyo Eletech Corporation). Note that the dimensions in figure 7 are somewhat different from those of the actual chip's mount pad.

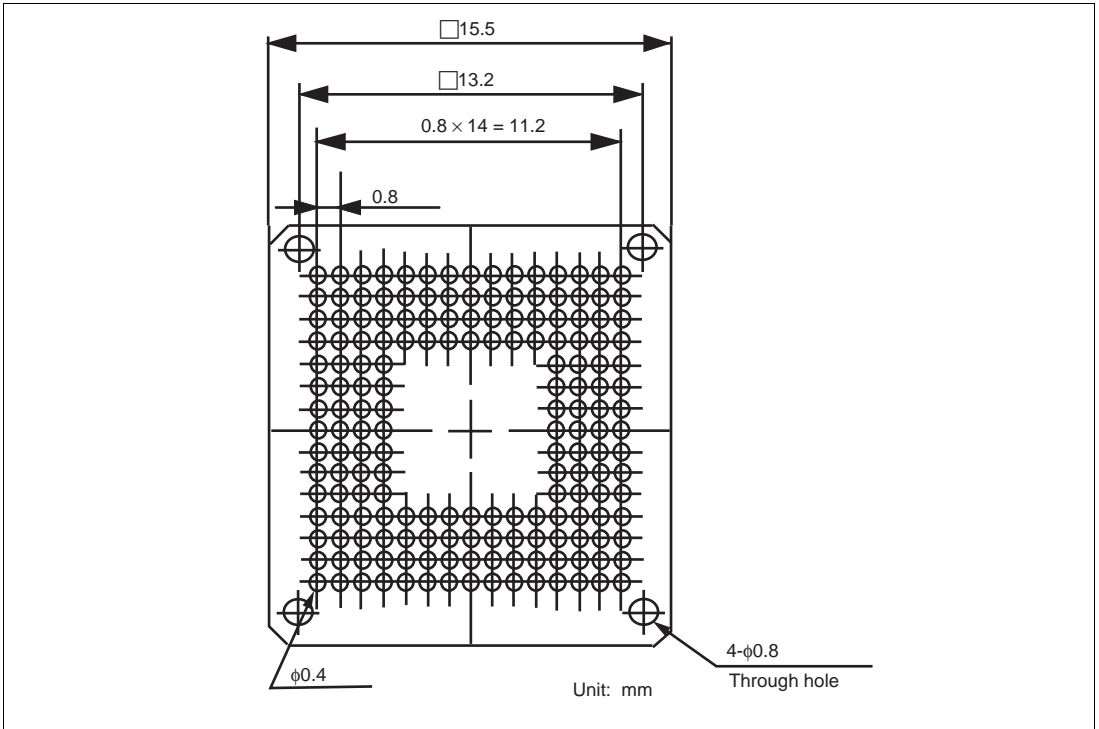


Figure 7 Recommended Dimensions for Mount Pad

2.4 Dimensions for User System Interface Cable Head

The dimensions for the user system interface cable head are shown in figure 8.

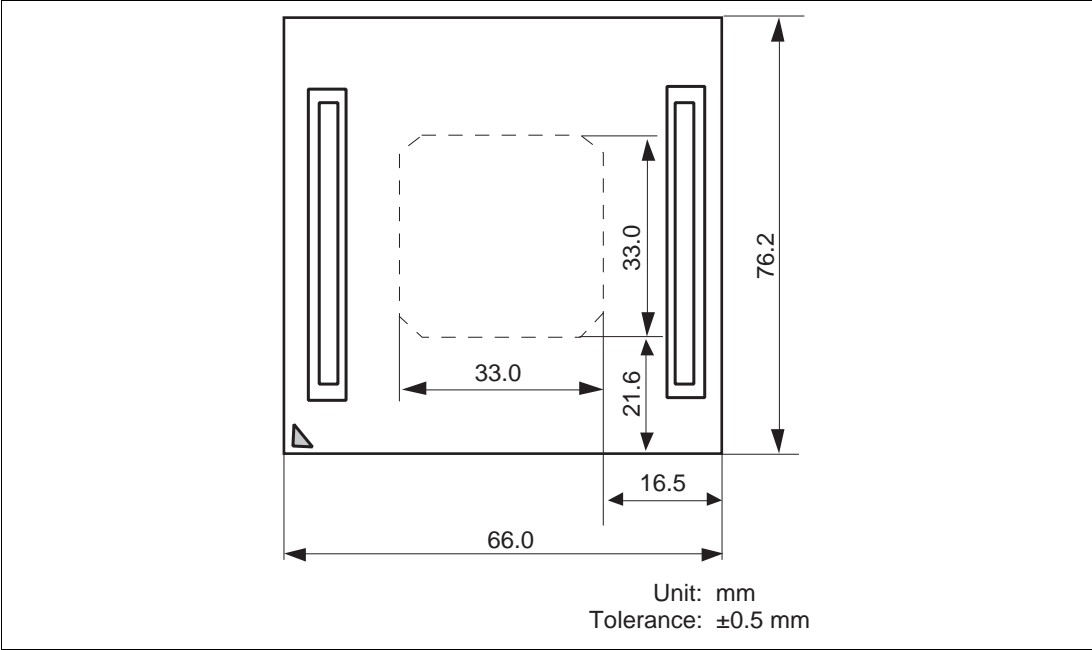


Figure 8 Dimensions for User System Interface Cable Head

2.5 Resulting Dimensions after Connecting User System Interface Cable

The resulting dimensions, after connecting the user system interface cable head to the user system, are shown in figure 9.

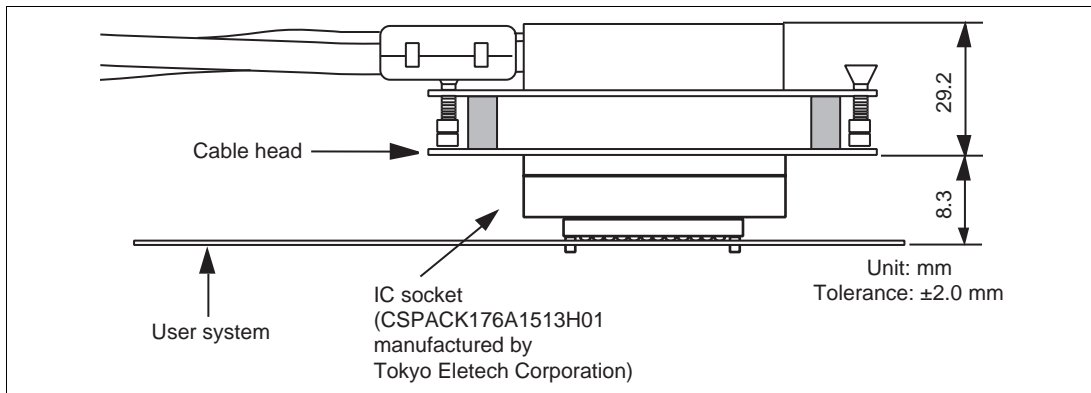


Figure 9 Resulting Dimensions after Connecting User System Interface Cable

Section 3 Installing the MCU to the User System

CAUTION

- 1. Check the location of pin 1 before inserting.**
- 2. Use a provided screwdriver.**
- 3. The tightening torque must be 0.054 N•m or less.
If the applied torque cannot be accurately measured, stop tightening when the force required to turn the screw becomes significantly greater than that needed when first tightening. If a screw is tightened too much, the screw head will break or an IC socket contact error will be caused by a crack in the IC socket solder.**
- 4. If the MCU does not operate correctly, cracks might have occurred in the solder.**

1. Attach the spacer and cover to the IC socket.
2. Place the spacer on the IC socket. Place the two guide pins of the spacer in the corresponding holes on the IC socket.
3. Place the MCU gently in the opening of the spacer. Be sure to correctly align pin 1 of the MCU with the IC socket. The solder balls of the MCU will then be in the correct locations relative to the connection pins of the IC socket.
4. Put the cover on the spacer. The four holes at the four corners of the spacer and of the cover must be aligned. Use the four screws to fasten the cover to the IC socket. Each screw in turn should be made a little tighter, alternating between screws on opposing corners. Use the screwdriver provided with the package. The torque in tightening must be 0.054 N•m or less.
5. When removing the cover from the IC socket, hold the side of the cover so that no stress is applied to the soldered connections between the IC socket and user system while the screws on the cover are being unscrewed. Use tweezers to remove the MCU from the opening in the spacer.

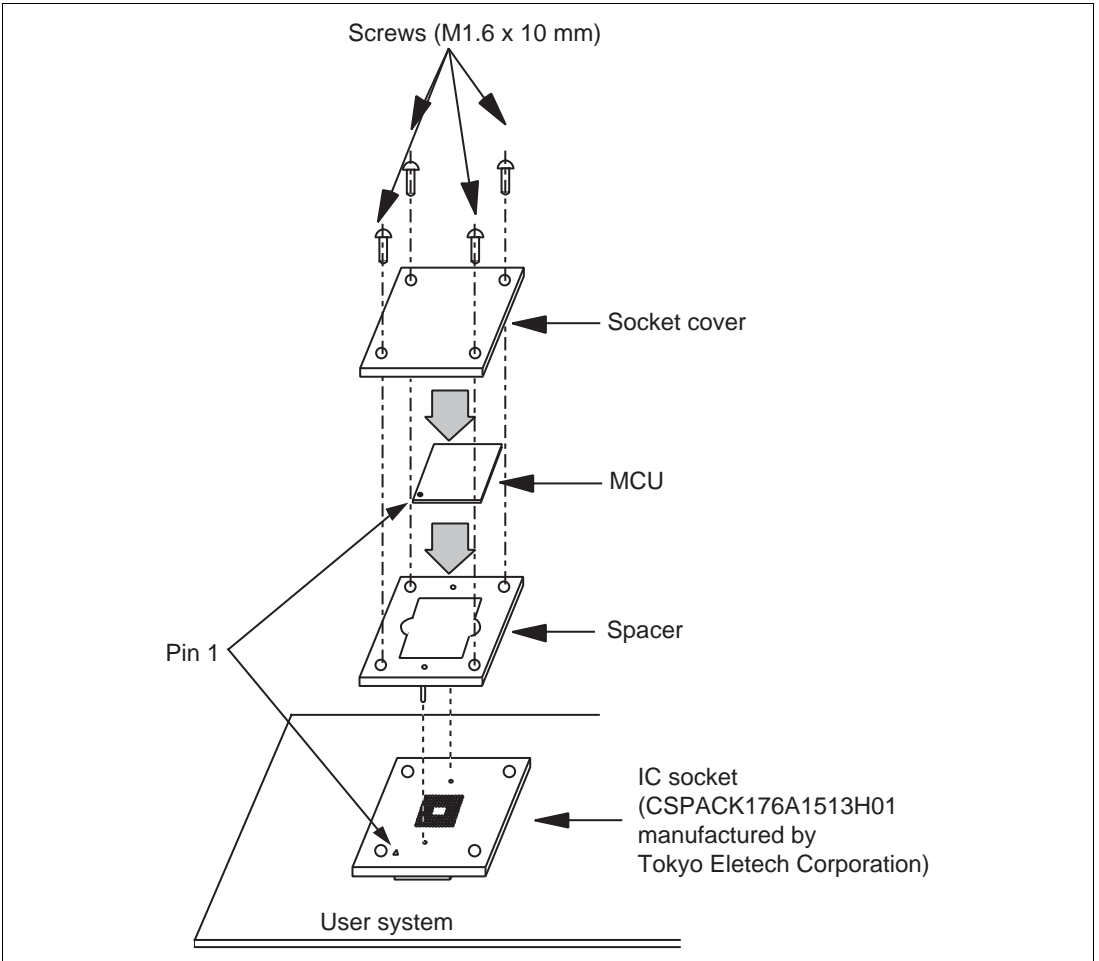


Figure 10 Installing MCU to User System

Section 4 Verifying Operation

1. Start up the emulator according to the procedures described in the H8S/2552 and H8S/2506 Group E6000 Emulator User's Manual (HS2556EPI61HE).
2. Verify the user system interface cable connections by accessing the external memory and ports to check the bus states of the pins. If an error is detected, recheck the soldered IC socket and the location of pin 1.
3. The emulator connected to this user system interface cable supports two kinds of clock sources as the MCU clock: an emulator internal clock and an external clock on the user system. For details, refer to the H8S/2556, H8S/2552, and H8S/2506 Group E6000 Emulator User's Manual (HS2556EPI61HE).

— To use the emulator internal clock

Select the clock in the emulator station with the [CLOCK] option in the [Configuration Properties] dialog box.

— To use the external clock on the user system

Select external clock (target or target/2) with the [CLOCK] option in the [Configuration Properties] dialog box, and supply the external clock from the user system to the emulator. Supply the external clock to the system clock by inputting the external clock from the EXTAL terminal on the cable head or connecting a crystal oscillator to the XTAL and EXTAL terminals. To supply the external clock to the subclock, connect the 32.768-kHz crystal oscillator to the OSC1 and OSC2 terminals. For details, refer to section 21, Clock Pulse Generator, in the H8S/2556, H8S/2552, and H8S/2506 Group Hardware Manual.

The user system interface cable has the oscillator circuits shown in figure 11.

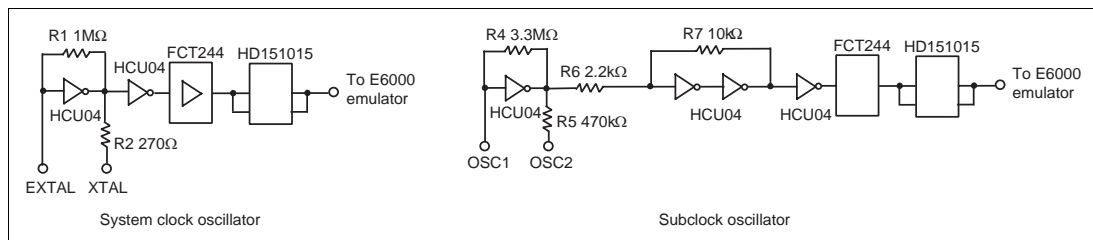


Figure 11 Clock Oscillator Circuits

Section 5 Notice

1. Make sure that pin 1 on the user system IC socket is correctly aligned with pin 1 on the cable head before inserting the cable head into the user system IC socket.
2. The dimensions of the recommended mount pad for the user system IC socket are different from those of the MCU.
3. This user system interface cable is specifically designed for the HS2556EPI61H emulator. Do not use this cable with any other emulator station.
4. To prevent breaking of wires in the cable body, do not place heavy or sharp metal objects on the user system interface cable.
5. While the emulator station is connected to the user system with the user system interface cable, force must not be applied to the cable head. Place the emulator station, user system interface cable, and user system as shown in the example in figure 12.

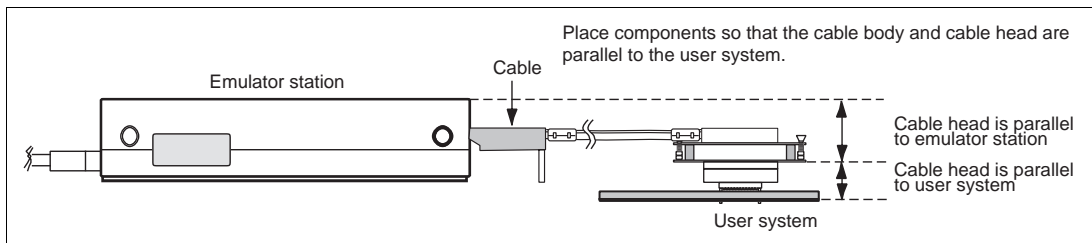


Figure 12 User System Interface Cable Location Example

6. The P1 jumper connector is used for testing. Do not remove the inserted jumper pin.

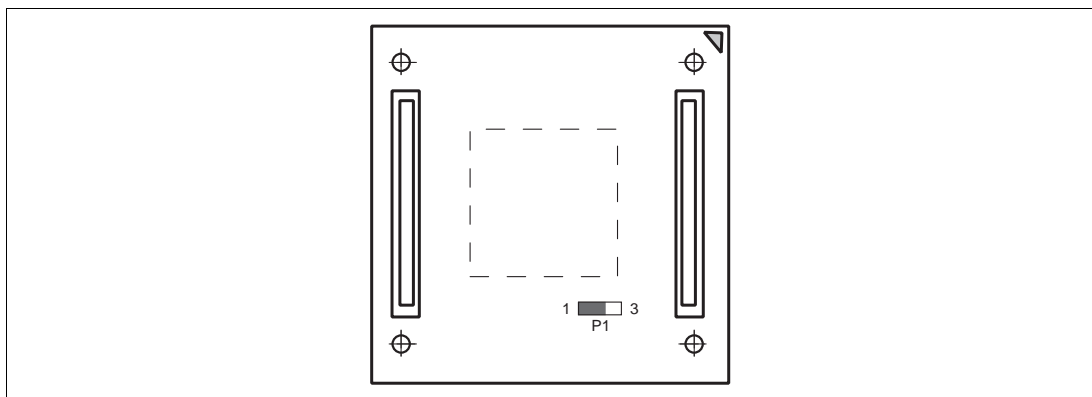


Figure 13 P1 Short Connector

**Renesas Microcomputer Development Environment System
User's Manual
H8S/2552, H8S/2506 Group BP-176V
User System Interface Cable for E6000 Emulator
HS2552ECB62H**

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User System Interface Cable for E6000 Emulator
HS2552ECB62H User's Manual**



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